SN65C3222, SN75C3222 3-V TO 5.5-V MULTICHANNEL RS-232 COMPATIBLE LINE DRIVER/RECEIVER

SLLS534B - MAY 2002 - REVISED OCTOBER 2004

- Operates With 3-V to 5.5-V V_{CC} Supply
- Operates Up To 1 Mbit/s
- Low Standby Current . . . 1 μA Typ
- External Capacitors . . . 4 × 0.1 μF
- Accepts 5-V Logic Input With 3.3-V Supply
- RS-232 Bus-Pin ESD Protection Exceeds ±15 kV Using Human-Body Model (HBM)
- Applications
 - Battery-Powered Systems, PDAs,
 Notebooks, Laptops, Palmtop PCs, and
 Hand-Held Equipment

(TOP VIEW) 20 PWRDOWN FΝΓ C1+[]2 19 🛮 V_{CC} 18 GND V+[]3 C1−∏4 17 DOUT1 16 **∏** RIN1 C2+∏5 C2- Π 6 15 **∏** ROUT1 V−**∏** 7 14 NC DOUT2 8 13 DIN1 RIN2 I 9 12 **∏** DIN2 ROUT2 ¶ 10 ∏ NC

DB, DW, OR PW PACKAGE

NC - No internal connection

description/ordering information

The SN65C3222 and SN75C3222 consist of two line drivers, two line receivers, and a dual charge-pump circuit with ± 15 -kV ESD protection pin to pin (serial-port connection pins, including GND). The devices provide the electrical interface between an asynchronous communication controller and the serial-port connector. The charge pump and four small external capacitors allow operation from a single 3-V to 5.5-V supply. The devices operate at data signaling rates up to 1 Mbit/s and a driver output slew rate of 24 V/ μ s to 150 V/ μ s.

The SN65C3222 and SN75C3222 can be placed in the power-down mode by setting $\overline{PWRDOWN}$ low, which draws only 1 μ A from the power supply. When the devices are powered down, the receivers remain active while the drivers are placed in the high-impedance state. Also, during power down, the onboard charge pump is disabled, V+ is lowered to V_{CC}, and V- is raised toward GND. Receiver outputs also can be placed in the high-impedance state by setting \overline{EN} high.

ORDERING INFORMATION

TA	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	0010 (D)40	Tube of 25	SN75C3222DW	7500000
	SOIC (DW)	Reel of 2000	SN75C3222DWR	75C3222
−0°C to 70°C	SSOP (DB)	Reel of 2000	SN75C3222DBR	CA3222
	TSSOP (PW)	Tube of 70	SN75C3222PW	CA2000
		Reel of 2000	SN75C3222PWR	CA3222
	SOIC (DW)	Tube of 25	SN65C3222DW	0500000
		Reel of 2000	SN65C3222DWR	65C3222
-40°C to 85°C	SSOP (DB)	Reel of 2000	SN65C3222DBR	CB3222
	TCCOD (DM)	Tube of 70	SN65C3222PW	CDagge
	TSSOP (PW)	Reel of 2000	SN65C3222PWR	CB3222

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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Function Tables

EACH DRIVER

IN	OUTPUT	
DIN	PWRDOWN	DOUT
Х	L	Z
L	Н	Н
Н	Н	L

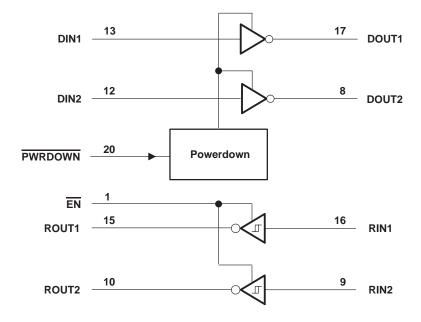
H = high level, L = low level, X = irrelevant, Z = high impedance

EACH RECEIVER

INPU	OUTPUT	
RIN	EN	ROUT
L	L	Н
Н	L	L
Х	Н	Z
Open	L	Н

H = high level, L = low level, X = irrelevant, Z = high impedance (off), Open = input disconnected or connected driver off

logic diagram (positive logic)



SN65C3222, SN75C3222 3-V TO 5.5-V MULTICHANNEL RS-232 COMPATIBLE LINE DRIVER/RECEIVER

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC} (see Note 1)	0.3 V to 6 V
Positive output supply voltage range, V+ (see Note 1)	
Negative output supply voltage range, V- (see Note 1)	0.3 V to –7 V
Supply voltage difference, V+ – V– (see Note 1)	13 V
Input voltage range, V _I : Drivers, EN, PWRDOWN	0.3 V to 6 V
Receivers	–25 V to 25 V
Output voltage range, VO: Drivers	
Receivers	0.3 V to V _{CC} + 0.3 V
Package thermal impedance, θ_{JA} (see Notes 2 and 3):	DB package 70°C/W
	DW package 58°C/W
	PW package 83°C/W
Operating virtual junction temperature, T _J	
Storage temperature range, T _{stq}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltages are with respect to network GND.

- 2. Maximum power dissipation is a function of T_J(max), θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is P_D = (T_J(max) T_A)/θ_{JA}. Operating at the absolute maximum T_J of 150°C can affect reliability.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4 and Figure 5)

				MIN	NOM	MAX	UNIT
	Owner houselfer me	V _{CC} = 3.3 V		3	3.3	3.6	.,
Supply voltage		V _{CC} = 5 V		4.5	5	5.5	V
.,	Deliver and control black level incort valtage	DIN EN BWBBOWN	V _{CC} = 3.3 V	2			.,
VIH	Driver and control high-level input voltage	DIN, EN, PWRDOWN	V _{CC} = 5 V	2.4			V
VIL	Driver and control low-level input voltage	DIN, EN, PWRDOWN				8.0	V
٧ _I	Driver and control input voltage	DIN, EN, PWRDOWN		0		5.5	V
٧ _I	Receiver input voltage			-25		25	V
TA	Operating free-air temperature	SN65C3222	_	-40		85	°C
		SN75C3222	_	0		70	C

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 5)

	PARAMETER	TEST CONDITIONS	MIN	TYP‡	MAX	UNIT
II	Input leakage current (EN, PWRDOWN)			±0.01	±1	μΑ
	Supply current	No load, PWRDOWN at VCC		0.3	1	mA
Icc	Supply current (powered off)	No load, PWRDOWN at GND		1	10	μΑ

[‡] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.



DRIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 5)

	PARAMETER	TEST	CONDITIONS	MIN	TYP†	MAX	UNIT
Vон	High-level output voltage	DOUT at $R_L = 3 \text{ k}\Omega$ to GND,	DIN = GND	5	5.4		V
VOL	Low-level output voltage	DOUT at R _L = $3 \text{ k}\Omega$ to GND,	DIN = V _{CC}	-5	-5.4		V
lн	High-level input current	VI = VCC			±0.01	±1	μΑ
IլL	Low-level input current	V _I at GND			±0.01	±1	μΑ
	Object of the first standard summer of the	V _{CC} = 3.6 V,	VO = 0 V		±35	±60	A
los	Short-circuit output current‡	V _{CC} = 5.5 V,	VO = 0 V		±35	±90	mA
r _O	Output resistance	V _{CC} , V+, and V- = 0 V,	$V_O = \pm 2 V$	300	10M		Ω
1	Output leakage current PWRDOWN = GND	$V_O = \pm 12 \text{ V}, V_{CC} = 3 \text{ V to } 3.6 \text{ V}$			±25		
loff		PWKDOWN = GND	$V_O = \pm 10 \text{ V}, V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$			±25	μΑ

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V \pm 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V \pm 0.5 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 4)

	PARAMETER	TEST CONDITIONS		MIN	TYP†	MAX	UNIT
			C _L = 1000 pF	250			
Maximum data rate (see Figure 1)		$R_L = 3 k\Omega$, One DOUT switching	$C_L = 250 \text{ pF}, \qquad V_{CC} = 3 \text{ V to } 4.5 \text{ V}$	1000			kbit/s
			$C_L = 1000 \text{ pF}, \qquad V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	1000			
t _{sk(p)}	Pulse skew§	C _L = 150 pF to 2500 pF	$R_L = 3 \text{ k}\Omega \text{ to } 7 \text{ k}\Omega,$ See Figure 2		300		ns
SR(tr)	Slew rate, transition region (see Figure 1)	R _L = 3 kΩ to 7 kΩ, V _{CC} = 3.3 V	C _L = 150 pF to 1000 pF	18		150	V/μs

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

\$ Pulse skew is defined as $|tp_{LH} - tp_{HL}|$ of each channel of the same device. NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.



[‡] Short-circuit durations should be controlled to prevent exceeding the device absolute power-dissipation ratings, and not more than one output should be shorted at a time.

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RECEIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 5)

	PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
Vон	High-level output voltage	$I_{OH} = -1 \text{ mA}$	V _{CC} – 0.6 V	V _{CC} – 0.1 V		V
VOL	Low-level output voltage	I _{OL} = 1.6 mA			0.4	V
V _{IT+}	Decision makes insure the seek and contrary	V _{CC} = 3.3 V		1.5	2.4	.,
	Positive-going input threshold voltage	$V_{CC} = 5 V$		1.8	2.4	V
\/	Negative-going input threshold voltage	V _{CC} = 3.3 V	0.6	1.2		.,,
VIT-		V _{CC} = 5 V	0.8	1.5		V
V _{hys}	Input hysteresis (V _{IT+} - V _{IT-})			0.3		V
l _{off}	Output leakage current	EN = V _{CC}		±0.05	±10	μΑ
rį	Input resistance	V _I = ±3 V to ±25 V	3	5	7	kΩ

† All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C. NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V \pm 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V \pm 0.5 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4)

	PARAMETER	TEST CONDITIONS	MIN TYPT MAX	UNIT
tPLH	Propagation delay time, low- to high-level output	$C_{L} = 150$ pF, See Figure 3	300	ns
tPHL	Propagation delay time, high- to low-level output	C _L = 150 pF, See Figure 3	300	ns
t _{en}	Output enable time	C_L = 150 pF, R_L = 3 kΩ, See Figure 4	200	ns
t _{dis}	Output disable time	C_L = 150 pF, R_L = 3 kΩ, See Figure 4	200	ns
t _{sk(p)}	Pulse skew [‡]	See Figure 3	300	ns

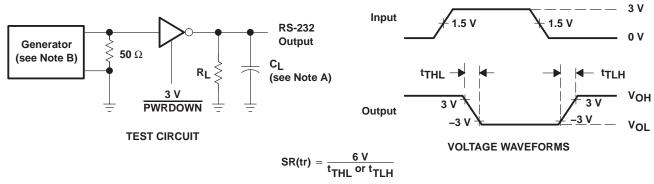
[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.



[‡] Pulse skew is defined as |tpLH - tpHL| of each channel of the same device.

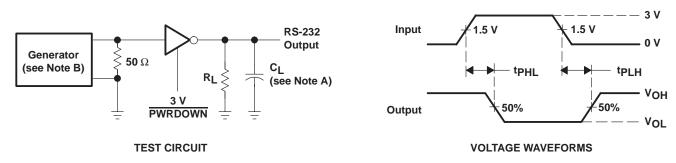
PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_O = 50~\Omega$, 50% duty cycle, $t_\Gamma \le 10$ ns. $t_f \le 10$ ns.

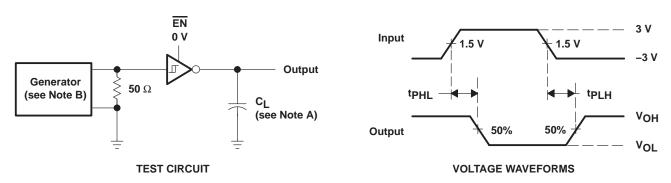
Figure 1. Driver Slew Rate



NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_f \le 10$ ns. $t_f \le 10$ ns.

Figure 2. Driver Pulse Skew



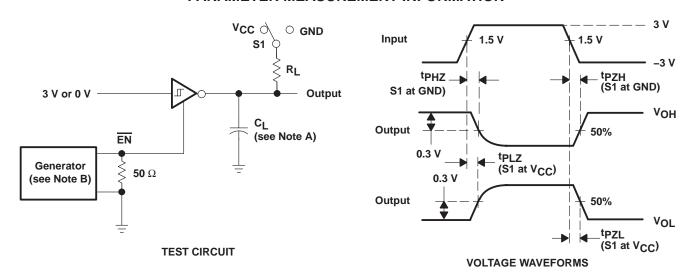
NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: $Z_O = 50 \Omega$, 50% duty cycle, $t_r \le 10$ ns, $t_f \le 10$ ns.

Figure 3. Receiver Propagation-Delay Times



PARAMETER MEASUREMENT INFORMATION

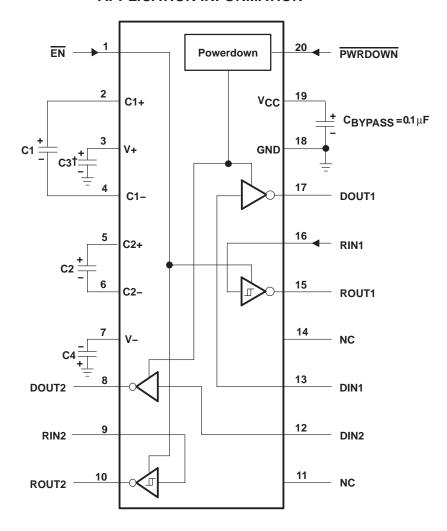


NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: $Z_O = 50 \ \Omega$, 50% duty cycle, $t_\Gamma \le 10 \ ns$, $t_f \le 10 \ ns$.

Figure 4. Receiver Enable and Disable Times

APPLICATION INFORMATION



 $^\dagger\text{C3}$ can be connected to VCC or GND.

NOTES: A. Resistor values shown are nominal.

B. NC - No internal connection

V_{CC} vs CAPACITOR VALUES

vcc	C1	C2, C3, and C4
3.3 V \pm 0.3 V	0.1 μ F	0.1 μ F
5 V ± 0.5 V	0.047 μ F	0.33 μF
3 V to 5.5 V	0.1 μ F	0.47 μ F

Figure 5. Typical Operating Circuit and Capacitor Values



DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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